

**Date: OCT-21-2021** P1/4

Semtech Corporation, 200 Flynn Road, Camarillo CA 93012						
Change Details						
Part Number(s) Affecte	ed:	Customer Part Number(s)	Affected: ⊠ N/A			
Please see the list on the next page.						
Description, Purpose a	and Effect of Chang	ge:				
Chipbond, a Semtech supplier, is expanding its laser marking capacity with the addition of a new laser marking machine. The new laser marking machine, EO CSM3302FC, is equipped with the same technology as the current machine, EO CSM2000/CSM3000.  Please see the following pages for more information.						
Change Classification	☐ Major ☐ Mino	Impact to Form, Fit, Function	☐ Yes   ⊠ No			
Impact to Data Sheet	☐ Yes ⊠ No	New Revision or Date	⊠ N/A			
Impact to Performance, Characteristics or Reliability:  This change does not impact performance, characteristics or reliability.						
Implementation Date	NOV-21-2021	Work Week	46			
Last Time Ship (LTS) Of unchanged product	N/A	Affecting Lot No. / Serial No. (SN)	N/A			
Sample Availability	N/A	Qualification Report Availability	N/A			
Supporting Documents for Change Validation/Attachments:  • N/A						
Inquire Authority						

Issuing Authority				
Semtech Business Unit:	Signal Integrity Product Group (SIP)			
Semtech Contact Info:	Pedro Jr. Bernas Quality Assurance pbernas@semtech.com (289) 856-9326 x1162			
FOR FURTHER INFORMATION & WORLDWIDE SALES COVERAGE: http://www.semtech.com/contact/index.html#support				



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Part Number(s) Affected					
1	GN2104SA-IBE3	11	GN2904S-IBTE3D	21	SX9311ICSTRT
2	GN2104SC-IBE3	12	SC21150ACSTRT	22	SX9311YICSTRT
3	GN2104SC-IBTE3D	13	SC33020HCSTRT	23	SX9311ZICSTRT
4	GN2104S-IBE3	14	SC725CSTRT	24	SX9320ICSTRT
5	GN2104S-IBTE3D	15	SX6100BCCSTRT	25	SX9322ICSTRT
6	GN2139C-IBE3	16	SX6202ACCSTRT	26	SX9323ICSTRT
7	GN2139C-IBTE3D	17	SX9210ICSTRT	27	SX9324ICSTRT
8	GN24L60-CSP-TR	18	SX9306ICBTRT	28	SX9325ICSTRT
9	GN24L61-CSP-TR	19	SX9310ICSTRT	29	SX9328ICSTRT
10	GN2904S-IBE3	20	SX9310ICSTRT-C	30	SX9330ICSTRT

#### **MACHINE COMPARISON**

	EO CSM2000 / 3000 (Current)	EO CSM3302FC (New)	
Machine			
Laser type	Green laser	Green laser	
Wavelength	532nm	532nm	
Maximum power	3W	5W	
Support Wafer size	6″~12″	8" / 12"	
Marking Accuracy	±75um	±50um	
Repeatability	±25um	±25um	
Marking Method	Direct Marking	Direct Marking	
Available wafer thickness	≥150um	≥150um	
Marking Depth	<5um	<5um	
Target dot size	40um	40um	
	01234	01234	
Laser marking appearance	56789	ABCDE	

<sup>\*</sup> Note: The new machine has two laser marking modules (Laser 1 & Laser 2) that will increase productivity. There is only one laser marking module in the current machine.



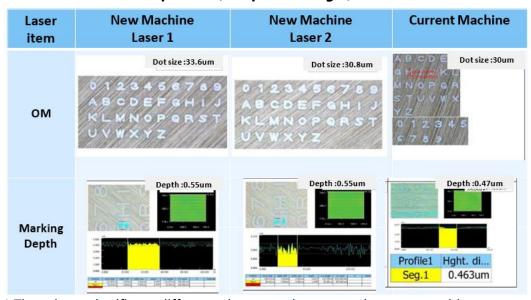
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#### **MARKING DEPTH Comparison (Sample Marking 1)**

Laser item	New Machine Laser 1	New Machine Laser 2	Current Machine
ом	Dot size:31.9um  0 1 2 3 4 5 6 7 4 9  A 9 C D E F Q H   J  KLMN O P Q R S T  UVWX Y Z	Dot size:30.8um 0 120456769 ABCDEFQHIJ	Dot size:35um  HILLIKU  NOPAA  TUVWX  YZ
Marking Depth	Dot size :3.4um	Dot size :4um	Dot size : 3.8um

<sup>\*</sup> There is no significant difference between the new and current machines.

#### **MARKING DEPTH Comparison (Sample Marking 2)**



<sup>\*</sup> There is no significant difference between the new and current machines.



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### **New Machine: Comparison of Laser 1 and Laser 2 markings (different fonts)**

Laser item	Font Arial size	Font Consolas size	Font Arial size	Font Consolas size	
	150*150 um	100*200um	150*150 um	100*200um	
	Sample Marking 1		Sample Marking 2		
Laser 1	01254SE749	0123456789	D123456789	0123456789	
	ABCDEFRHIJ	ABCDEFGHIJ	ABCDEFGHIJ	ABCDEFGHIJ	
	KLMNOPARST	KLMNOPORST	KLMNOPGRST	KLMNOPORST	
	UVWXYZ	UVWXYZ	UVWXYZ	UVWXYZ	
Laser 2	0123456788 ABCDEFRHIJ KLMNOPGAST UVWXYZ	0123456789 ABCDEFGHIJ KLMNOPQRST UVNXYZ	ABCDEERIN	0123456789 ABCDEFCHIJ KLMNOPQRST UVWXYZ	

<sup>\*</sup> There is no significant difference between the two laser markings.